

Title (en)
System for applying varnishes with relief

Title (de)
System zum Auftragen von Lacken mit Relief

Title (fr)
Système pour appliquer des vernis avec un relief

Publication
EP 2251205 A2 20101117 (EN)

Application
EP 10160104 A 20100415

Priority
ES 200901220 A 20090514

Abstract (en)
The invention relates to a system for applying varnishes with relief, of the type forming a decorative application formed by a bottom layer (5) and a structured layer (6) with relief forms, performing the supply of said layers (5 and 6) at the same time with one and the same application roller (1) provided with recesses (2), combining said application roller (1) with a supply of the product to be applied which fills the recesses (2) and incorporates a layer (4) of product on the surface of the application roller (1), such that with the product of the layer (4) the bottom layer (5) is formed and with the product of the recesses (2) the structured layer (6) is formed in the decorative application.

IPC 8 full level
B41M 3/06 (2006.01); **B05C 1/08** (2006.01); **B27N 7/00** (2006.01)

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Citation (applicant)
• US 5178928 A 19930112 - GOTO HIDEO [JP], et al
• EP 1645339 A1 20060412 - FRITZ EGGER GMBH & CO [AT], et al
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AL BA ME RS

DOCDB simple family (publication)
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